

JC10 Rec'd PCT/PTO 07 FEB 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Akira Hashimoto : Art Unit:
Serial No.: To Be Assigned : Examiner:
Filed: Herewith :
FOR: METHOD FOR MANUFACTURING CERAMIC :
SUBSTRATE :

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

S I R :

Prior to examination, please amend the above application as follows:

IN THE SPECIFICATION:

After the title and before the first paragraph, please insert the following paragraph:

THIS APPLICATION IS A U.S. NATIONAL PHASE APPLICATION OF PCT
INTERNATIONAL APPLICATION PCT/JP01/04818.

IN THE DRAWINGS:

Please delete pages "10/11" and "11/11" of the drawings, also labeled as "Reference numerals in the drawings" in its entirety.

IN THE CLAIMS:

Please replace claims 3, 6, 9, 10, 13, 14, and 17-19 with the following amended claims:

3. (Amended) The method of claim 1, further comprising the steps of:

forming a via-conductor through forming a through-hole in the un-sintered green sheet;
and

connecting the conductive pattern to the via conductor.

6. (Amended) The method of claim 4, further comprising the steps of:

forming a via-conductor through forming a through-hole in the un-sintered green sheet;

and

connecting the conductive pattern to the via-conductor.

9. (Amended) The method of claim 7, further comprising the steps of:

forming a via-conductor through forming a through-hole in the un-sintered green sheet;

and

connecting the conductive patterns to the via-conductor.

10. (Amended) The method of claim 7, further comprising the steps of:

forming a via-conductor through forming a through-hole in the sintered substrate; and

connecting the conductive pattern to the via-conductor.

13. (Amended) The method of claim 11, further comprising the step of:

forming a via-conductor through forming a through-hole in the un-sintered green sheet;

and

connecting the conductive patterns to the via-hole conductor.

14. (Amended) The method of claim 11, further comprising the steps of:

forming a via-conductor through forming a through-hole in the sintered ceramic substrate; and

connecting the conductive pattern to the via-conductor.

17. (Amended) The method of claim 15, wherein the first intaglio and the second intaglio are identical to each other.

18. (Amended) The method of claim 15, further comprising the steps of:

forming a first via-conductor through forming a through-hole in the un-sintered green sheet; and

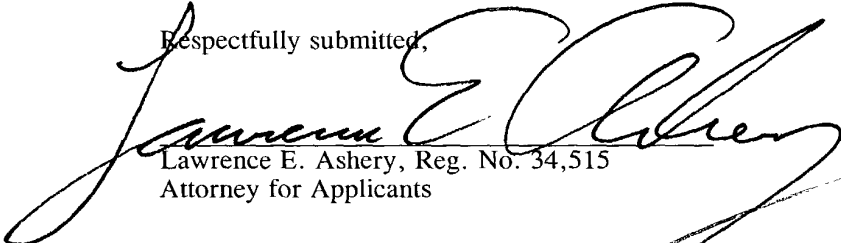
connecting at least one of the first and second conductive patterns to the first via-conductor.

19. (Amended) The method of claim 15, further comprising the steps of:

forming a second via-conductor through forming a through-hole in the sintered ceramic substrate; and

connecting at least one of said first and second conductive patterns to the second via-conductor.

Respectfully submitted,


Lawrence E. Ashery, Reg. No. 34,515
Attorney for Applicants

LEA/fp

Enclosure: Version With Markings Showing Changes Made

Dated: February 7, 2002

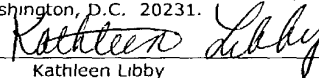
Suite 301, One Westlakes, Berwyn
P.O. Box 980
Valley Forge, PA 19482-0980
(610) 407-0700

The Assistant Commissioner for Patents is hereby
authorized to charge payment to Deposit Account No.
18-0350 of any fees associated with this
communication.

EXPRESS MAIL Mailing Label Number: **EL 743 541 775 US**

Date of Deposit: **February 7, 2002**

I hereby certify that this paper and fee are being deposited, under 37 C.F.R. § 1.10 and with sufficient postage, using the "Express Mail Post Office to Addressee" service of the United States Postal Service on the date indicated above and that the deposit is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.


Kathleen Libby

VERSION WITH MARKINGS SHOWING CHANGES MADE

Please replace claims 3, 6, 9, 10, 13, 14, and 17-19 with the following amended claims:

3. (Amended) The method of claim 1-~~or~~2, further comprising the steps of:
- forming a via-conductor through forming a through-hole in the un-sintered green sheet;
- and
- connecting the conductive pattern to the via conductor.
6. (Amended) The method of claim 4-~~or~~5, further comprising the steps of:
- forming a via-conductor through forming a through-hole in the un-sintered green sheet;
- and
- connecting the conductive pattern to the via-conductor.
9. (Amended) The method of claim 7-~~or~~8, further comprising the steps of:
- forming a via-conductor through forming a through-hole in the un-sintered green sheet;
- and
- connecting the conductive patterns to the via-conductor.
10. (Amended) The method of ~~any one of claims~~ claim 7-~~to~~9, further comprising the steps of:
- forming a via-conductor through forming a through-hole in the sintered substrate; and
- connecting the conductive pattern to the via-conductor.
13. (Amended) The method of claim 11-~~or~~12, further comprising the step of:
- forming a via-conductor through forming a through-hole in the un-sintered green sheet;
- and

connecting the conductive patterns to the via-hole conductor.

14. (Amended) The method of ~~any one of claim~~ claims 11 to 13, further comprising the steps of:

forming a via-conductor through forming a through-hole in the sintered ceramic substrate; and

connecting the conductive pattern to the via-conductor.

17. (Amended) The method of ~~claim 15 or 16~~, wherein the first intaglio and the second intaglio are identical to each other.

18. (Amended) The method of ~~any one of claims~~ claim 15 to 17, further comprising the steps of:

forming a first via-conductor through forming a through-hole in the un-sintered green sheet; and

connecting at least one of the first and second conductive patterns to the first via-conductor.

19. (Amended) The method of ~~any one of claims~~ claim 15 to 18, further comprising the steps of:

forming a second via-conductor through forming a through-hole in the sintered ceramic substrate; and

connecting at least one of said first and second conductive patterns to the second via-conductor.